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(54) METHOD OF FORMING GERMANIUM ANTIMONY TELLURIUM FILM

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(57)**ABSTRACT**

A method of forming a germanium antimony tellurium (GeSbTe) layer includes forming a germanium antimony (GeSb) layer by repeatedly performing a GeSb supercycle; and forming the GeSbTe layer by performing a tellurization operation on the GeSb layer, wherein the GeSb supercycle includes performing at least one GeSb cycle; and performing at least one Sb cycle, the GeSbTe has a composition of Ge₂Sb_{2+a}Te_{5+b}, in which a and b satisfy the following relations: -0.2<a<0.2 and -0.5<b<0.5.

